

## Sintering densification and properties of Al<sub>2</sub>O<sub>3</sub>/Al cermet materials via powder metallurgy method

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Cermet materials are important new engineering materials with combined advantages of ceramics and metals. In this study, Al<sub>2</sub>O<sub>3</sub>/Al cermet materials were prepared through powder metallurgy. The effect of sintering technology on the properties of Al<sub>2</sub>O<sub>3</sub>/Al cermet materials was analyzed as basis for preparing high-performance cermet materials. Results showed that when the sintering temperature was increased from 700 °C to 1000 °C under holding time for 1 h, the densification degree and hardness of Al<sub>2</sub>O<sub>3</sub>/Al cermet materials decreased and the electric resistivity increased. In the microstructure of Al<sub>2</sub>O<sub>3</sub>/Al cermet materials, Al particles were larger and continuously distributed, whereas the Al<sub>2</sub>O<sub>3</sub> particles were smaller and discontinuously distributed. When the holding time was increased under sintering temperature of 700 °C, the densification degree and hardness of Al<sub>2</sub>O<sub>3</sub>/Al cermet materials also increased, and the electric resistivity decreased. When 25 wt% Al<sub>2</sub>O<sub>3</sub>/Al cermet materials were sintered at 700 °C for 3 h, the densification degree was higher, with hardness of 2203 HV and electric resistivity of 0.0159 Ω • m.

**Key words:** Cermet materials, Alumina, Aluminum, Sintering densification, Electric resistivity.

### Introduction

Cermet is a heterogeneous composite material, composed of metal or alloy and one or more ceramic phases, wherein the latter accounts for about 15%-85% of the volume of the material. When prepared at a certain temperature, the metal and ceramic phases dissolve extremely weak [1-3]. Cermet ceramic maintains to be extremely hard, wear-resistant, corrosion-resistant, heat-resistant, oxidation-resistant, and chemically stable, whereas its metal material allows it to be extremely strong, tough, and thermally and electrically conductive; non-metallic composition makes the ceramic-metal composites extremely hard, thermally strong, and wear-resistant; solid particles in cermet, combined with the metal phase, provides high strength and plasticity, thereby creating a high-performance engineering material [4-5]. The performance of ceramic-metal composites depends on the properties of the metal and ceramic, their volume percentages, bonding properties, and bonding strength of the phase interface [6-7].

As one of the most widely used ceramic materials, alumina ceramic, which has abundant raw materials, is extremely strong and hard, less dense, and chemically

stable. However, its brittleness hinders its application. Strong metal toughening of alumina ceramic is the most commonly used technical means. Aluminum (Al)-based composite material is based on Al or Al alloy as the matrix and its fiber or particle as a reinforcement of the homogeneous mixture, with highly specific strength, specific modulus, fatigue resistance, extreme toughness and impact resistance, high temperature, excellent wear resistance and more. Al<sub>2</sub>O<sub>3</sub>/Al metal-ceramic matrix composites are lightweight, extremely strong, ductile, tough, and aluminum-processed; alumina ceramics are extremely strong, hard, heat-resistant, wear-resistant, corrosion-resistant, and chemically stable; therefore, the Al<sub>2</sub>O<sub>3</sub>/Al metal matrix composites in the modern industrial production have an increasingly important role [8-10]. In this paper, the compactness of Al<sub>2</sub>O<sub>3</sub>/Al cermet was improved for the development of its wear resistance and low thermal conductivity characteristics.

### Experimental Materials and Methods

The raw materials used for the experiment were Al powder, produced by Tianjin Kemico Chemical Reagent Co., Ltd., with an average particle size of 40 μm and an analytical grade of pure Al<sub>2</sub>O<sub>3</sub> powder, produced by Shanghai 54 Chemical Reagent Factory, with an average particle size of 10 μm. To make a batch, 25% of Al<sub>2</sub>O<sub>3</sub> powder and 75% of Al powder were mixed

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on a mixer at 100 r/min for 2 h, and the agate ball was used as the milling medium. The mixed powder was dry pressured into  $\text{Ø } 10 \times 10 \text{ mm}$  mold at 10 MPa for 15 min. The molded sample was placed into the ZT-50-22 vacuum sintering furnace using different sintering processes for densification. The sintered sample is prepared into a rectangular parallelepiped, placed vertically when inlaid, and coarsely ground on both upper and lower surfaces of the embedded sample, so that the cermet is exposed on both surfaces of the embedded sample, and finally polished for use. The microstructure of the sample was observed with TESCAN VEGA II scanning electron microscope. The surface hardness of the sample was measured by HV-1000 Vickers hardness tester. The Electric resistivity of the sample was measured by CHT3540 DC resistance tester.

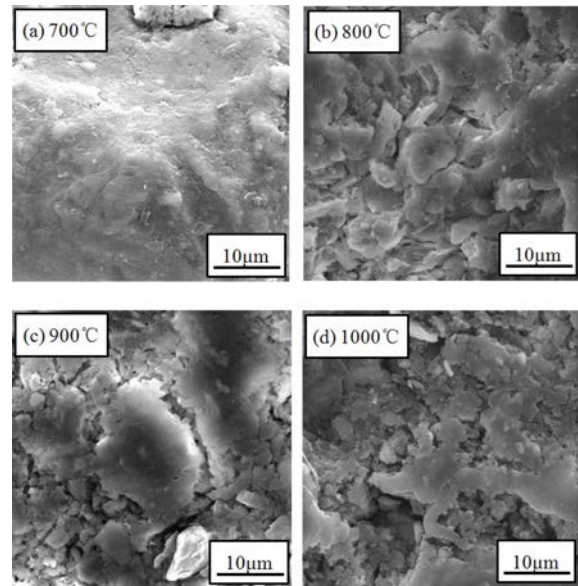
## Results and Discussion

### Sintering Densification of $\text{Al}_2\text{O}_3/\text{Al}$ Cermet Materials

Table 1 shows the relative density of  $\text{Al}_2\text{O}_3/\text{Al}$

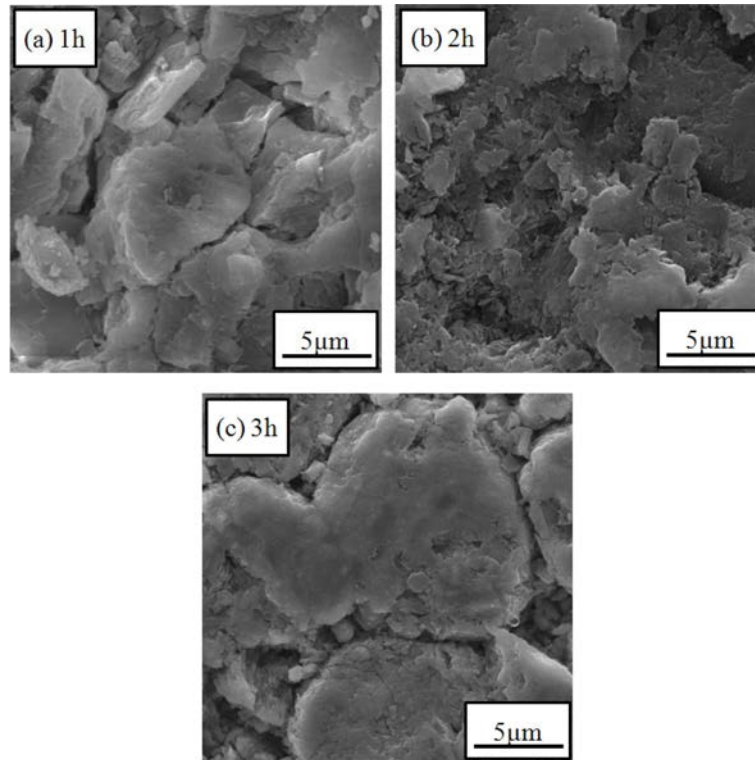
**Table 1.** Relation density of prepared sample under different sintering temperatures.

Temperature / $^{\circ}\text{C}$	700	700	700	800	900	1000
Holding time/h	1	2	3	1	1	1
Relative density/%	92.52	95.18	96.21	90.59	87.46	85.27



**Fig. 1.** Effect of sintering temperature on the microstructure of  $\text{Al}/\text{Al}_2\text{O}_3$  metal ceramics.

cermets prepared under different sintering conditions. The microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets prepared at different sintering temperature for 1 h is shown in Fig. 1. As shown in Tab.1, the sintering temperature gradually rose from 700  $^{\circ}\text{C}$  to 1000  $^{\circ}\text{C}$ , and in the microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets, the degree of densification gradually reduced. As shown in Fig. 1, the particles, which were larger and continuously distributed, were metal Al,



**Fig. 2.** Effect of holding time on the microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  metal ceramics.

distributed, were  $\text{Al}_2\text{O}_3$ . The Al particles served as the matrix phase, and the  $\text{Al}_2\text{O}_3$  particles served as the enhanced phase. As the temperature rose from 700 °C, the densities decreased. Because the melting point of Al was 660 °C and the melting point of  $\text{Al}_2\text{O}_3$  was 2,050 °C [11-12] above sintering, Al powder completely melted, while the  $\text{Al}_2\text{O}_3$  powder did not. The powders bonding along the way without sintering densification were combined loosely. In this case, Al was a dense phase relative to  $\text{Al}_2\text{O}_3$ , and  $\text{Al}_2\text{O}_3$  was a non-dense phase relative to Al. The melted Al enveloped the  $\text{Al}_2\text{O}_3$  powder to form an Al-based cermet. Al content in higher cases could fully wrap  $\text{Al}_2\text{O}_3$ , which formed a more continuous distribution of the block, resulting in a higher density of the organizational structure. The Al was set to 700 °C just over its melting point to ensure that the Al was both molten and suitable. Therefore, as the temperature increased, the more compact and the more mobile the Al was. This phenomenon is due to the vacuum sintering of negative green body pressure being more negative, making molten Al precipitation easier and subsequently resulting in a looser microstructure of the metal ceramics.

The microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  cermet obtained by sintering at 700 °C for different time periods is shown in Fig. 2. As shown in Tab.1, the microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  metal ceramics was denser as the holding time was prolonged. The reason is that in the case of a certain sintering temperature, the amount of molten Al in the body is almost constant. With longer holding time, the Al liquid has enough time to enter the pores for filling for metal ceramic densification, as depicted in Fig. 2.

#### Hardness of $\text{Al}_2\text{O}_3/\text{Al}$ cermet materials

Table 2 shows the results of the hardness tests of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets with different sintering temperatures for 1 h. Tab.2 shows that the sintering temperature gradually increased from 700 °C to 1000 °C, and the hardness of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets gradually decreased. The reason is that the hardness tested is the surface hardness, which depends on the density of the sample to some extent; thus, the tendency of the change is consistent with that of the microstructure of the  $\text{Al}_2\text{O}_3/\text{Al}$  cermet.

Table 3 shows the hardness test results of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets with sintering temperature of 700 °C under different holding time conditions. At 700 °C, the longer the holding time, the higher the hardness value. With prolonged holding time, the melted Al fully encapsulated the alumina and formed a relatively continuous distribution of the blocks, resulting in a higher density of the organizational structure, thereby increasing the hardness.

#### Electric resistivity of $\text{Al}_2\text{O}_3/\text{Al}$ cermet materials

Table 4 shows the results of the electric resistivity measurements of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets obtained by holding

**Table 2.** Hardness of prepared sample under different sintering temperatures.

Temperature/°C	700	800	900	1000
Hardness/HV	2056	824	647	503

**Table 3.** Hardness of prepared sample under different holding time conditions.

Holding time/h	1	2	3
Hardness/HV	2056	2125	2203

**Table 4.** Electric resistivity of prepared sample under different sintering temperatures.

Temperature /°C	700	800	900	1000
Electric resistivity / $\Omega\cdot\text{m}$	0.0452	0.0547	0.0701	0.1099

**Table 5.** Electric resistivity of prepared sample under different holding time conditions.

Holding time/h	1	2	3
Electric resistivity / $\Omega\cdot\text{m}$	0.0452	0.0214	0.0159

at different sintering temperatures for 1 h. The electric resistivity of  $\text{Al}_2\text{O}_3/\text{Al}$  cermets gradually increased as the sintering temperature gradually increased from 700 °C to 1000 °C. Because of the low electric resistivity of Al and the high resistivity of alumina, the higher the temperature, the more suitable for Al melted at 700 °C to form a continuous distribution of blocks with a high degree of densification of the microstructure. As a result, the resistance at a lower rate allowed the temperature of sintering samples to remain due to the worse degree of microstructure densification, resulting in higher resistivity.

Table 5 shows the  $\text{Al}_2\text{O}_3/\text{Al}$  cermet electric resistivity test results with sintering temperature of 700 °C under different holding time conditions. At 700 °C, the longer the holding time, the lower the rate of the electric resistance of  $\text{Al}_2\text{O}_3/\text{Al}$  cermet, which shows that with longer holding time, the resistivity decreased and the electrical properties improved. As the holding time prolonged, the melted Al fully encapsulated the alumina and formed a relatively continuous distribution of blocks, resulting in a higher density with high organizational structure and subsequently improved the electrical properties.

### Conclusions

To sum up, the microstructure densification degree of  $\text{Al}_2\text{O}_3/\text{Al}$  cermet decreases gradually as the hardness decreases and the electric resistivity increases under sintering temperature from 700 °C to 1000 °C for 1 h. In the microstructure of  $\text{Al}_2\text{O}_3/\text{Al}$  cermet materials, the Al particles are larger and continuously distributed, whereas the  $\text{Al}_2\text{O}_3$  particles are smaller and discontinuously

distributed. At 700 °C with prolonged holding time, the microstructure becomes denser, and a higher hardness indicated lower electric resistivity. When sintered at 700 °C for 3 h, a 25 wt% of  $Al_2O_3/Al$  cermet was obtained. The microstructure densified to a high degree with a hardness of 2203 HV and a electric resistivity of  $0.0159 \Omega \cdot m$ .

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